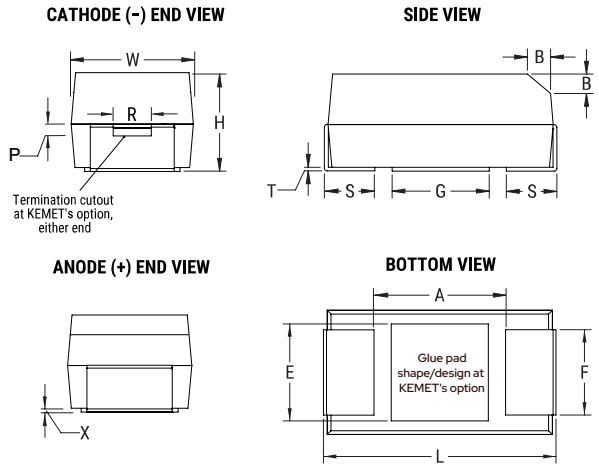
T493D157K010BC6420

T493 HRA, Tantalum, MnO2 Tantalum, HRA, 150 uF, 10%, 10 VDC, SMD, MnO2, Molded, High Reliability, B (0.1%/1000 Hrs), 100 mOhms, 3.1 mm, 1.3 mm, 2817 / 7343



Click here for the 3D model.

General Information	
Series	T493 HRA
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, High Reliability
Features	High Reliability
RoHS	No
Prop 65	**WARNING:** Cancer and reproductive harm - https://www.p65warnings.ca.gov/ .
SCIP Number	652b281f-d242-4453-bc44-0655d646cec3
Termination	Hot Solder Dipped
AEC-Q200	No
Typical Component Weight	412.33 mg
Notes	P and R dimensions represents the minimum solderable area of the termination surface entirely below cutout (if one is present).

Dimensions	
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
H	2.8mm +/-0.3mm
T	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.8mm MIN
B	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
P	0.5mm MIN
R	1mm REF
X	0.1mm +/-0.1mm REF

Specifications	
Capacitance	150 uF
Tolerance	10%
Voltage DC	10 VDC (85C), 6.7 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	8% 120Hz 25C
Failure Rate	B (0.1%/1000 Hrs)
ESR	0.1 Ohms (100kHz 25C)
Ripple Current	1225 mA (rms, 100kHz 25C)
Leakage Current	15 uA (5min 25°C)
Testing and Reliability	10 Cycles Surge Current Testing At -55C And +85C Before Weibull

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	500

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